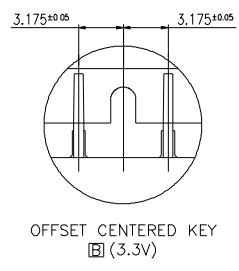
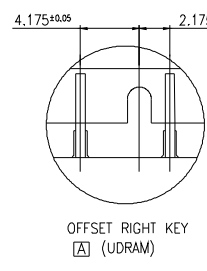
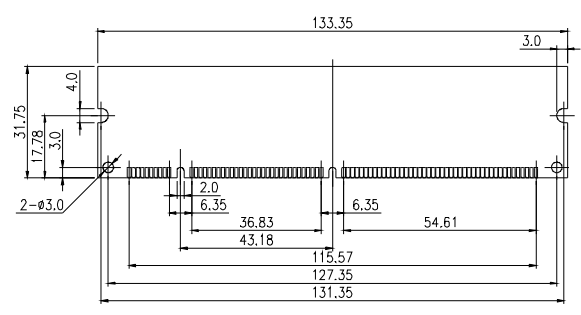
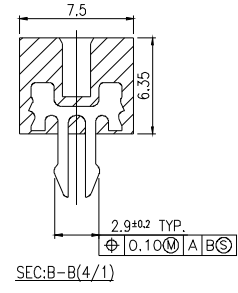
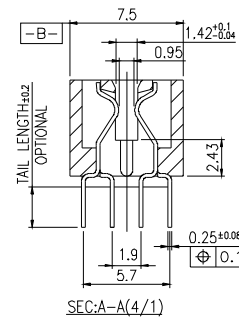
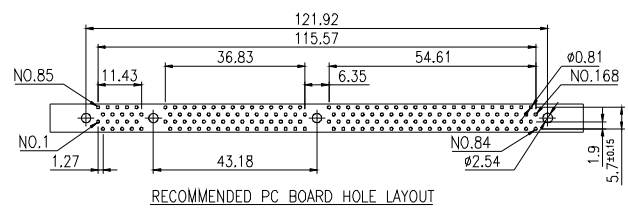
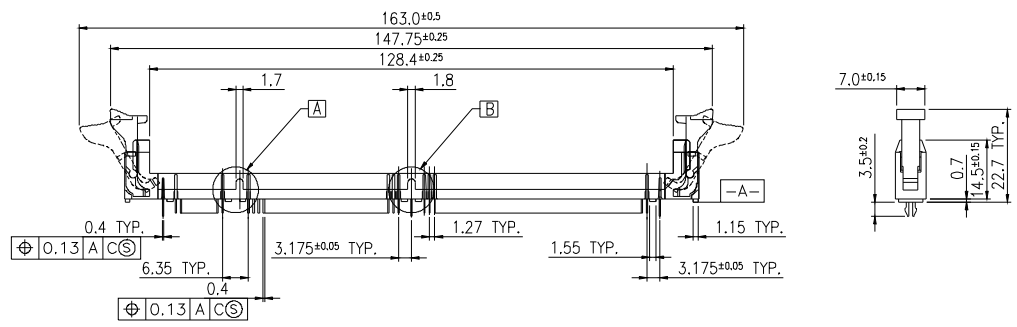
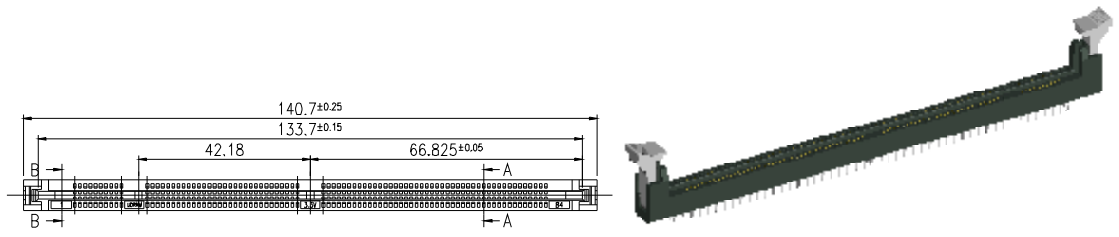


**DIMM SOCKET
CONNECTOR**

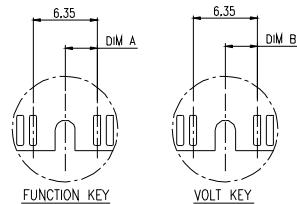
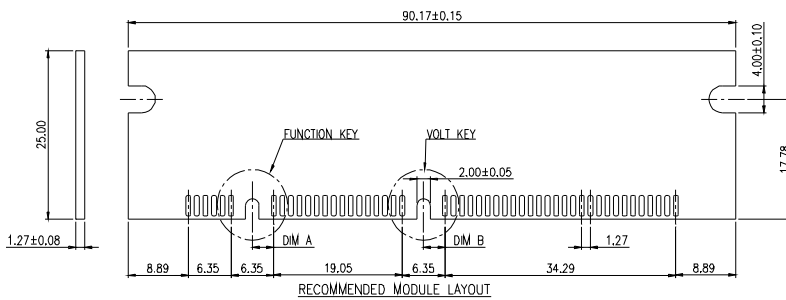
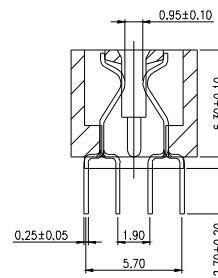
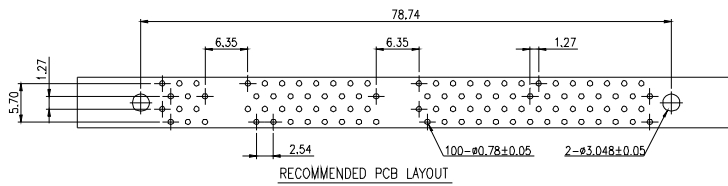
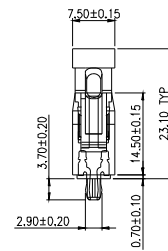
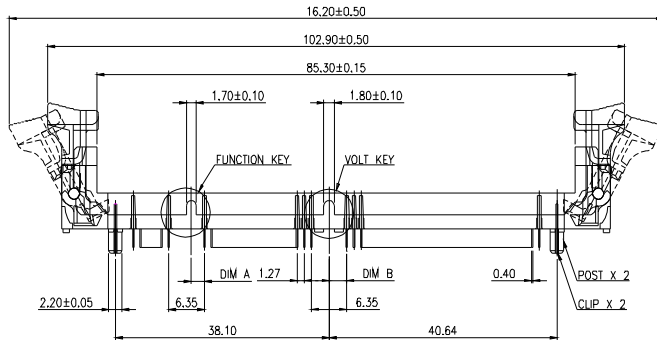
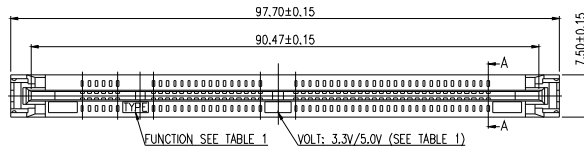
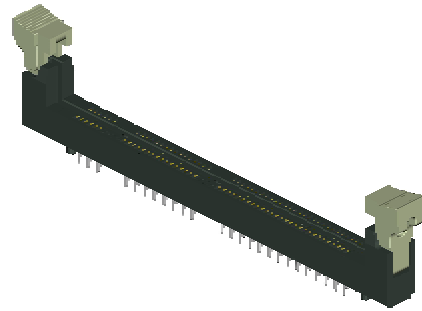
DIMM 1X3 SERIES STRAIGHT TYPE - P



DIMM	1X3	P	168	GX	X	X
DIMM SOCKET		PCB TYPE P: STRAIGHT TYPE	NO. OF PINS 168	CONTACT PLATING OPTION GfT: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G30I: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL	VOLTAGE 3: 3.3V 5: 5.0V	HOUSING MATERIAL N: NYLON-66 (STANDARD) L: LCP P: PBT
SERIES NO. 1: LATCH TYPE, HIGH LATCH X: TAIL LENGTH OPTIONS -0: 2.7mm -3: 3.0mm -4: 4.1mm 3: FUNCTION KEY, UDRAM(STANDARD)						

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 1X3 SERIES STRAIGHT TYPE - P

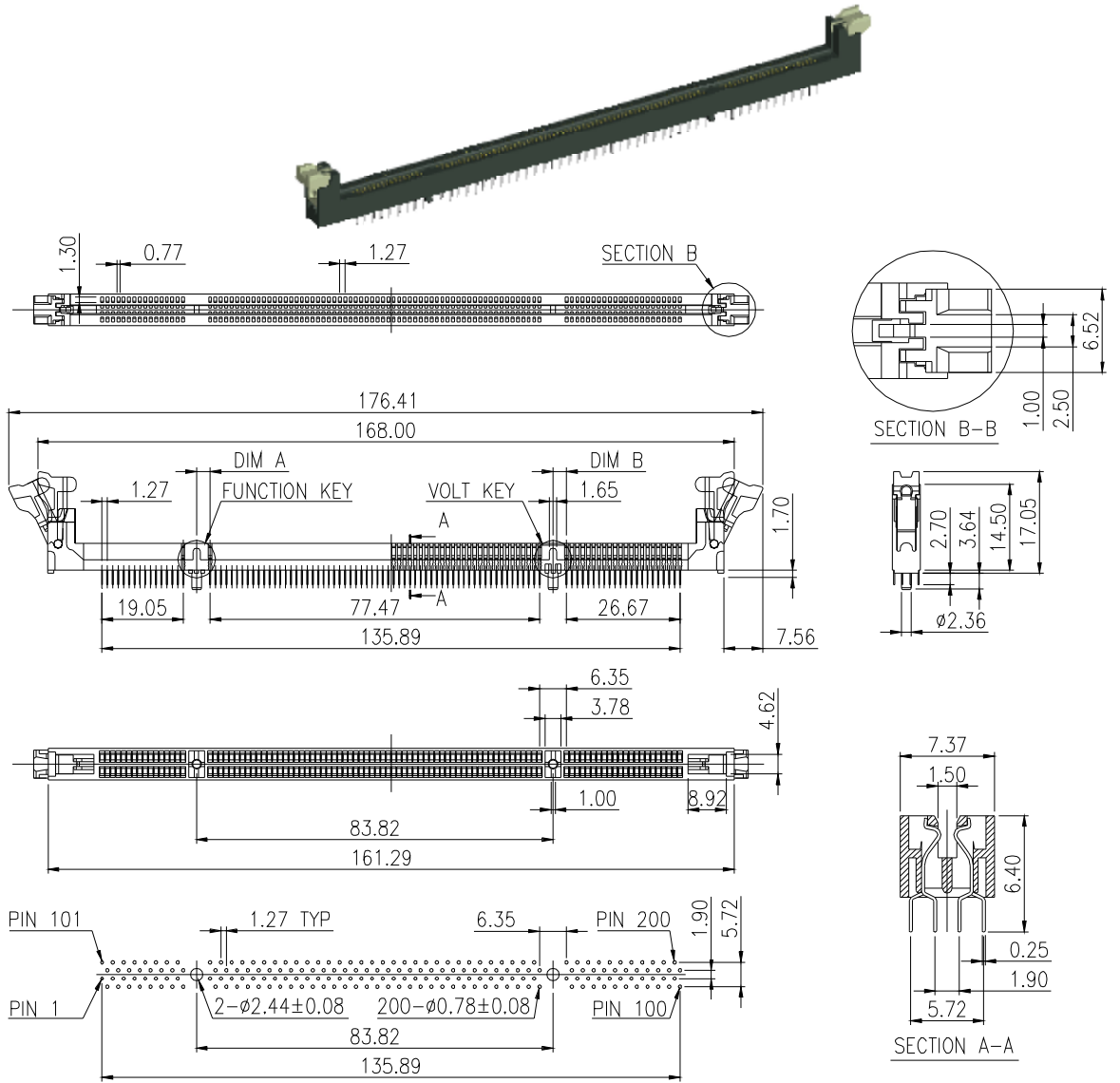


MODULE KEY CONFIGURATION	DIM A	DIM B	MODULE KEY CONFIGURATION	DIM A	DIM B
STANDARD DRAM, 5 VOLT (DRAM)	3.175	4.175	STANDARD DRAM, 3.3 VOLT (DRAM)	3.175	3.175
SYNC.DRAM, 5 VOLT (SDRAM)	4.175	4.175	SYNC.DRAM, 3.3 VOLT (SDRAM)	4.175	3.175
NON-STANDARD DRAM, 5 VOLT (UDRAM)	2.175	4.175	NON-STANDARD DRAM, 3.3 VOLT (UDRAM)	2.175	3.175

DIMM	10X	P	100	Gft	X	L
DIMM SOCKET		PCB TYPE P: STRAIGHT TYPE	NO. OF PINS 100	CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL	VOLTAGE 3: 3.3V (STANDARD) 5: 5.0V	HOUSING MATERIAL L: LCP (STANDARD)
SERIES NO. 1: LATCH TYPE, HIGH LATCH 0X: FUNCTION KEY -01: SDRAM -02: DRAM -03: UDRAM (STANDARD)						

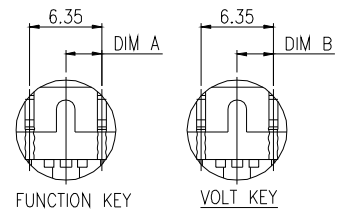
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 10X SERIES STRAIGHT TYPE - P



RECOMMENDED PCB LAYOUT

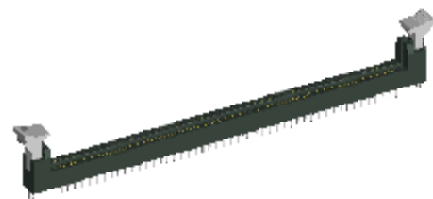
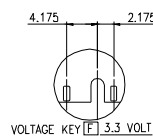
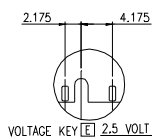
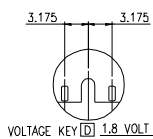
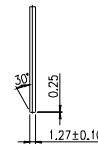
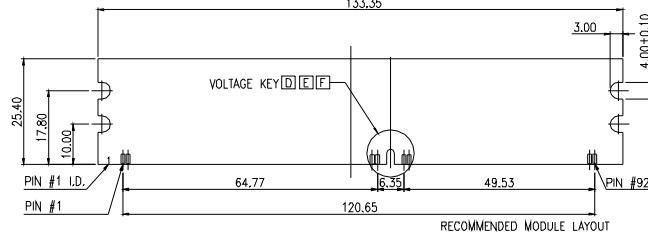
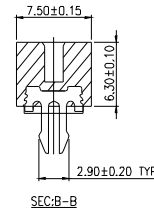
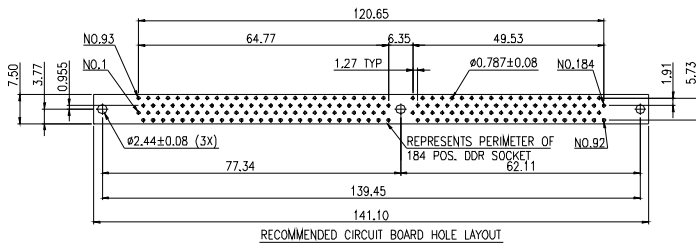
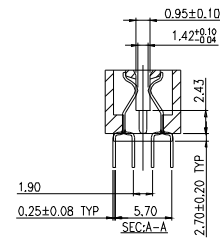
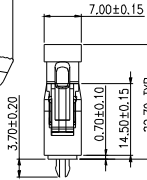
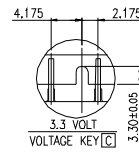
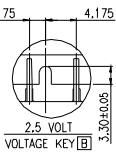
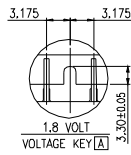
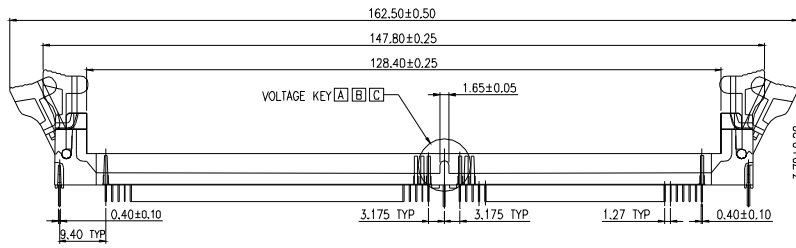
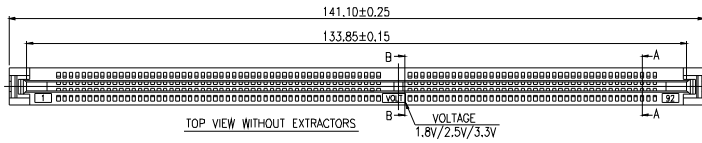
MODULE KEY CONFIGURATION	DIM A	DIM B	MODULE KEY CONFIGURATION	DIM A	DIM B
STANDARD DRAM, 5 VOLT (DRAM)	3.175	4.175	STANDARD DRAM, 3.3 VOLT (DRAM)	3.175	3.175
SYNC.DRAM, 5 VOLT (SDRAM)	4.175	4.175	SYNC.DRAM, 3.3 VOLT (SDRAM)	4.175	3.175
NON-STANDARD DRAM, 5 VOLT (UDRAM)	2.175	4.175	NON-STANDARD DRAM, 3.3 VOLT (UDRAM)	2.175	3.175



DIMM	10X	-	P	200	-	X	X
DIMM SOCKET	SERIES NO. 1: LATCH TYPE, HIGH LATCH 0X: FUNCTION KEY -01: SDRAM -02: DRAM -03: UDRAM (STANDARD)		PCB TYPE P: STRAIGHT TYPE	NO. OF PINS 200		VOLTAGE 3: 3.3V (STANDARD) 5: 5.0V	HOUSING MATERIAL N: NYLON-66 (STANDARD) L: LCP P: PBT
				CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL			

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

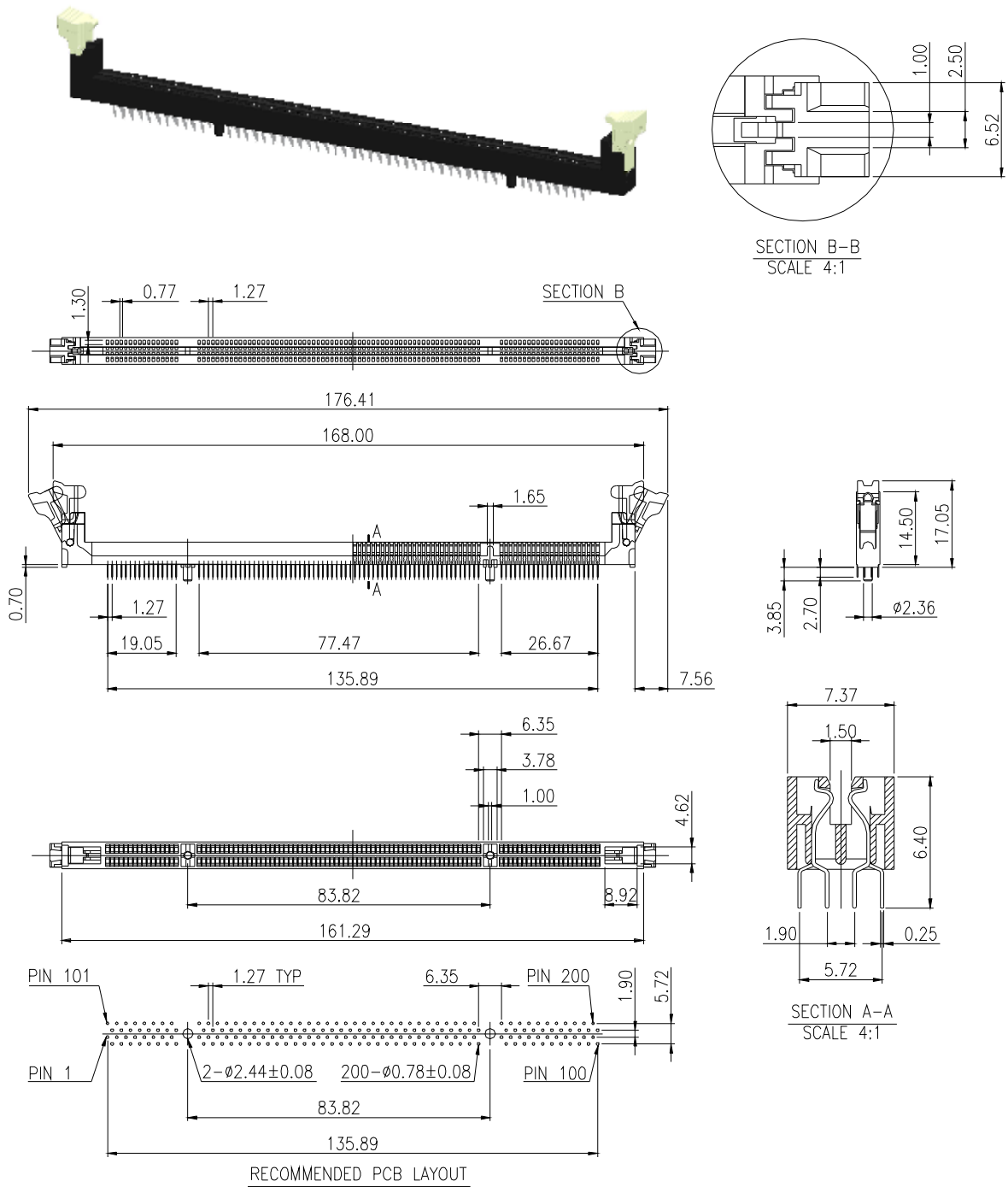
DIMM 104 SERIES STRAIGHT TYPE - P



DIMM	104	P	184	Gft	X	X
DIMM SOCKET	SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM	PCB TYPE P: STRAIGHT TYPE	NO. OF PINS 184	CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL	VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V	HOUSING MATERIAL N: NYLON 66 (STANDARD) L: LCP

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

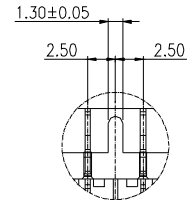
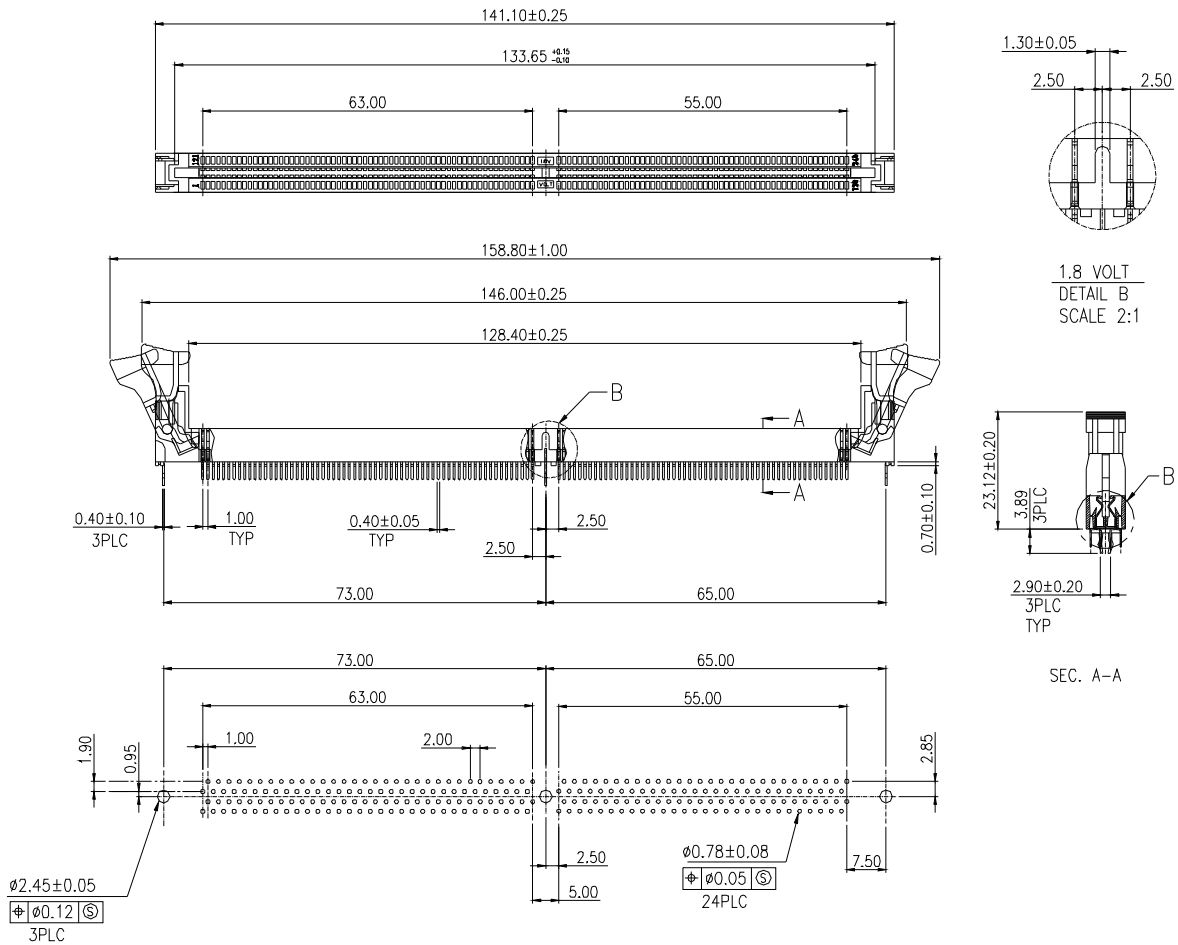
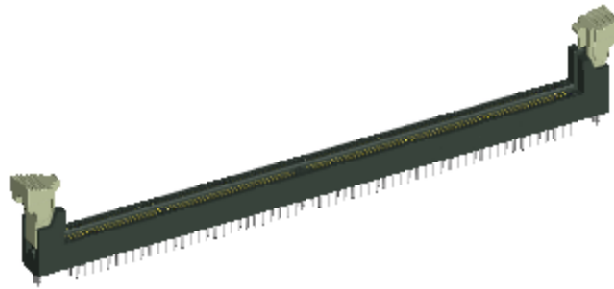
DIMM 104 SERIES STRAIGHT TYPE - P



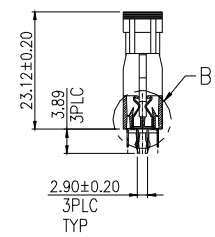
DIMM	104	P	200	Gft	X	X
DIMM SOCKET	SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM	PCB TYPE P: STRAIGHT TYPE	NO. OF PINS 200	CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL	VOLTAGE 1: 1.8V 2: 2.5V	HOUSING MATERIAL N: NYLON 66 (STANDARD) L: LCP P: PBT

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES STRAIGHT TYPE - P



1.8 VOLT
DETAIL B
SCALE 2:1

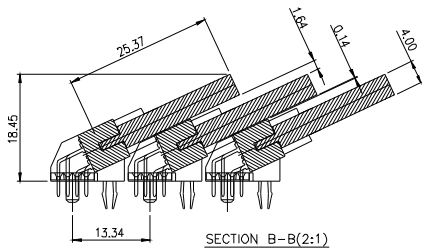
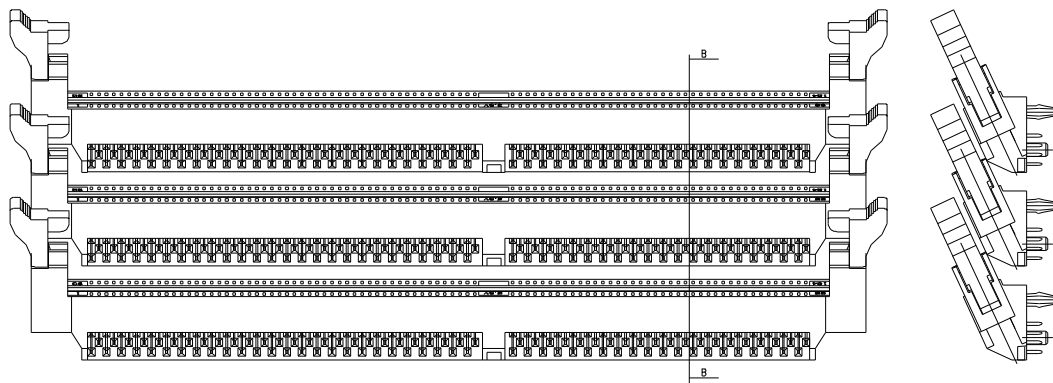
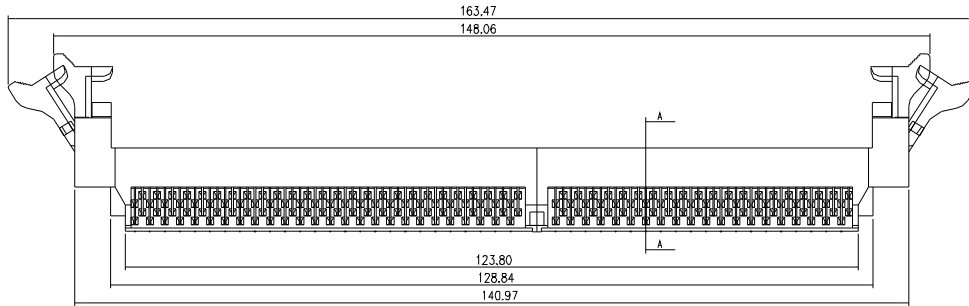
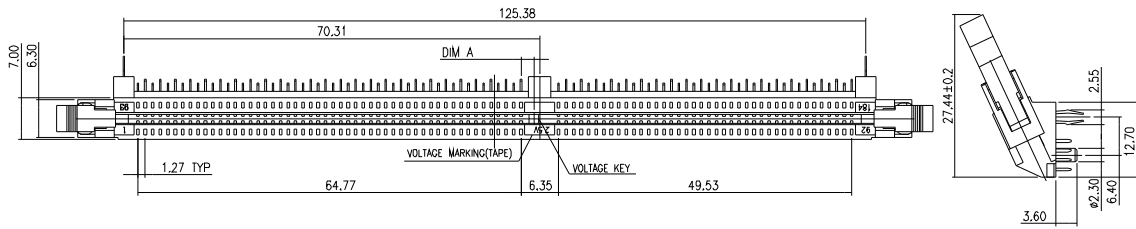


SEC. A-A

DIMM	104	P	240	GX	X	X	X
DIMM SOCKET		PCB TYPE P: STRAIGHT TYPE	NO. OF PINS 240		VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V		COLOR TYPE 0: WHITE 1: BLACK
SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM		CONTACT PLATING OPTION Gf: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL			HOUSING MATERIAL N: NYLON 66 (STANDARD)		

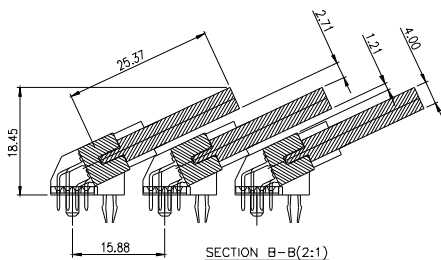
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr



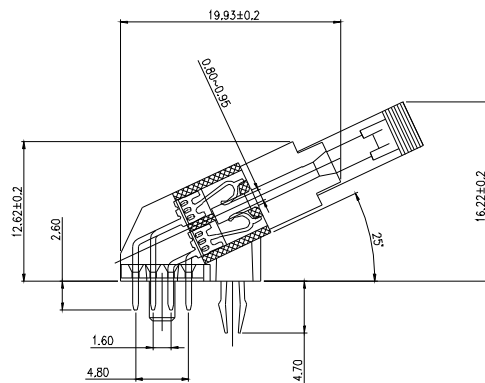
SECTION B-B(2:1)

MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 WILL LEAVE APPROXIMATELY 0.14 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



SECTION B-B(2:1)

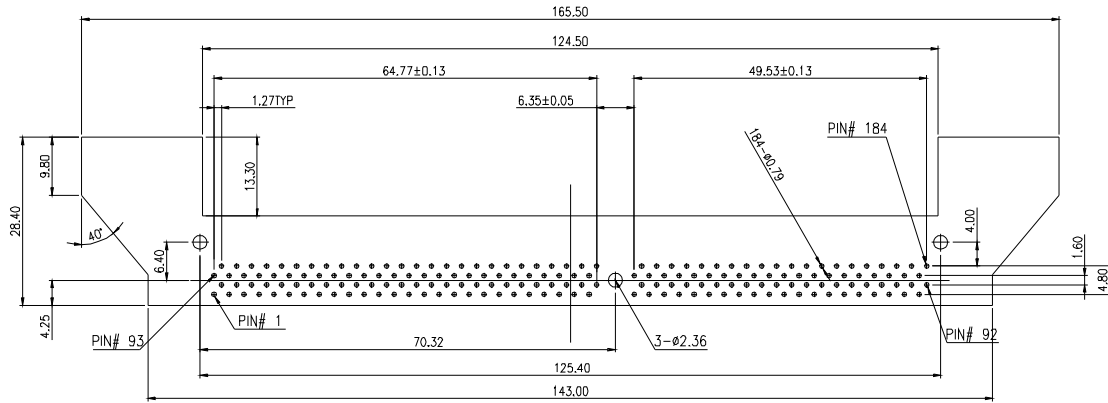
MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 15.88 WILL LEAVE APPROXIMATELY 1.21 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



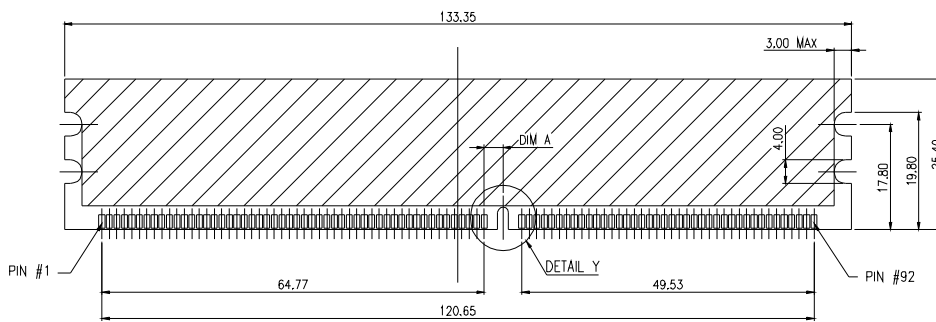
SECTION A-A(2:1)

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

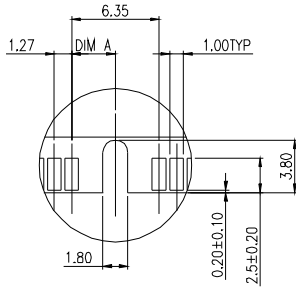
DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr



P.C. BOARD HOLE LAYOUT

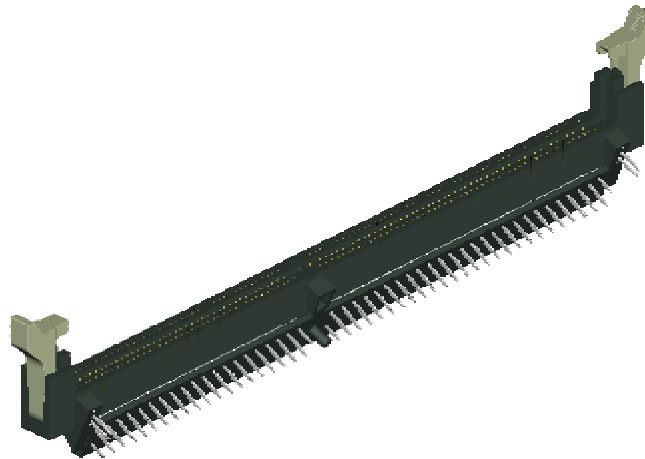


DAUGHTER CARD REQUIREMENT



DETAIL Y
SCALE 2:1

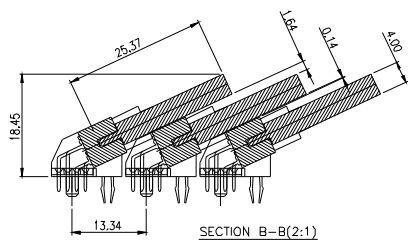
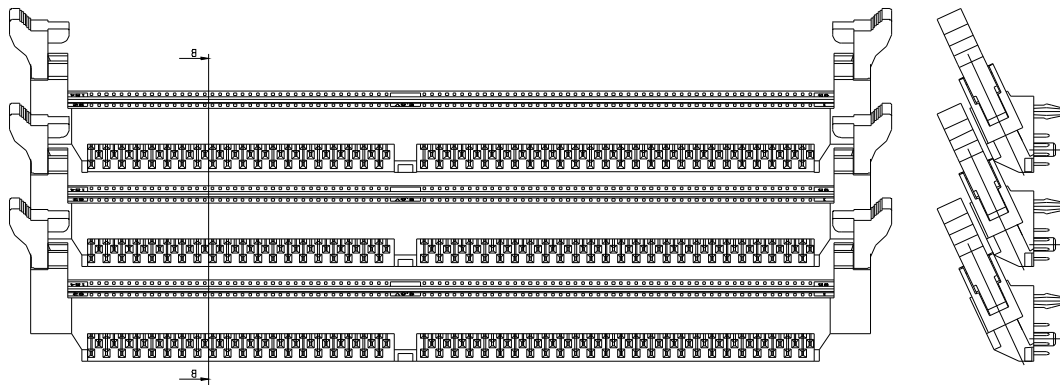
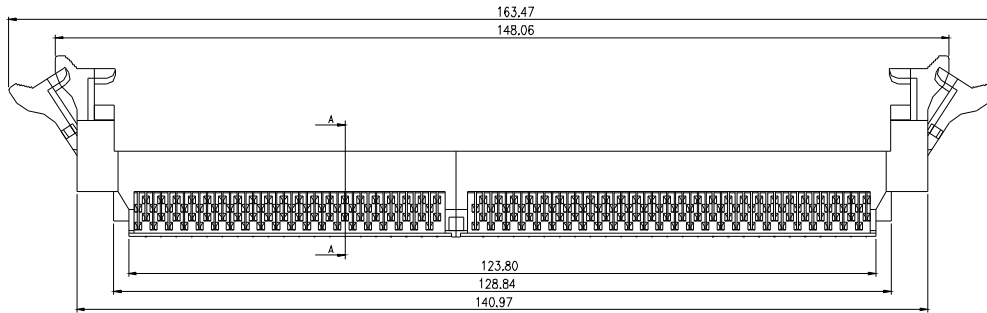
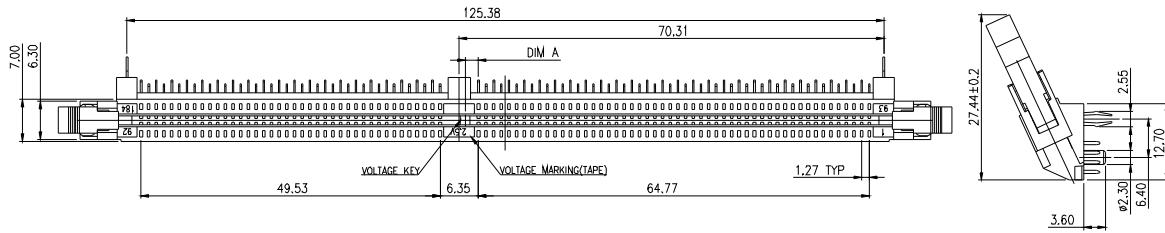
VOLTAGE	DIM A
1.8V	3.175
2.5V	2.175
3.3V	4.175



DIMM	104	Pr	184	GX	X	L
DIMM SOCKET		PCB TYPE Pr: RIGHT ANGLE 25 DEGREE TYPE	NO. OF PINS 184		VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V	HOUSING MATERIAL L: LCP
SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM		CONTACT PLATING OPTION Gf: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL				

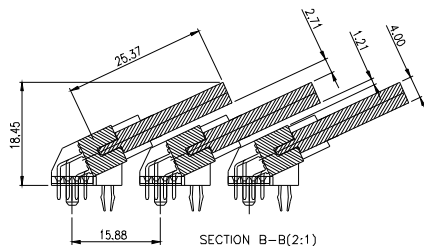
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



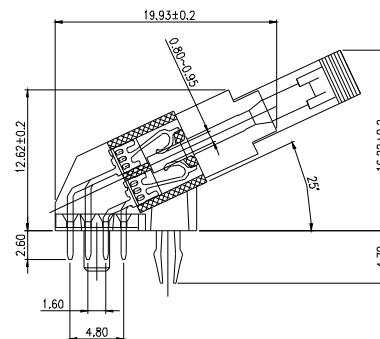
SECTION B-B(2:1)

MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 WILL LEAVE APPROXIMATELY 0.14 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



SECTION B-B(2:1)

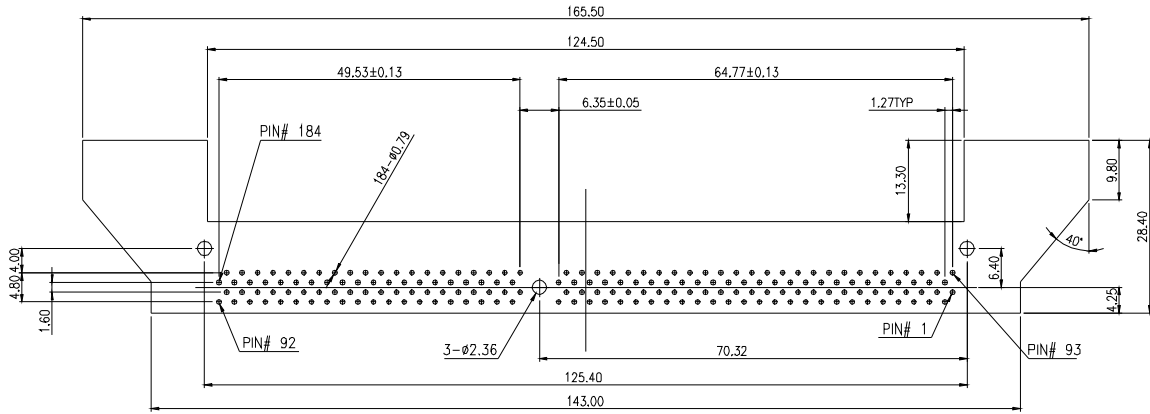
MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 15.88 WILL LEAVE APPROXIMATELY 1.21 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



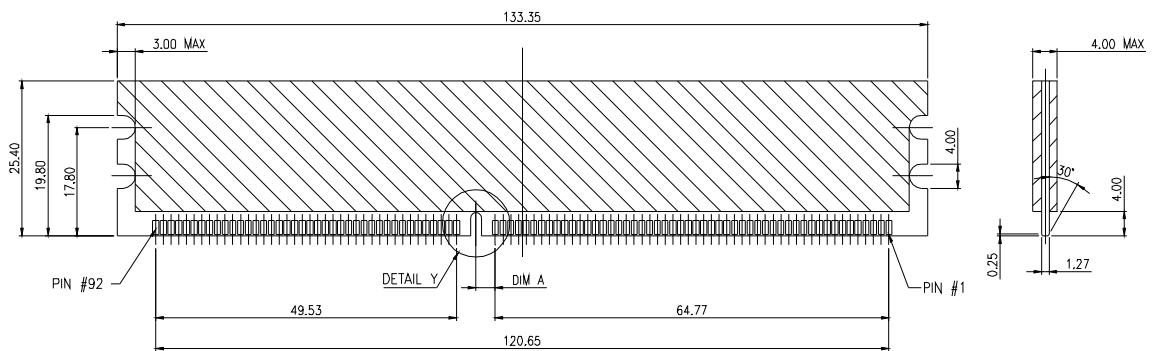
SECTION A-A(2:1)

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

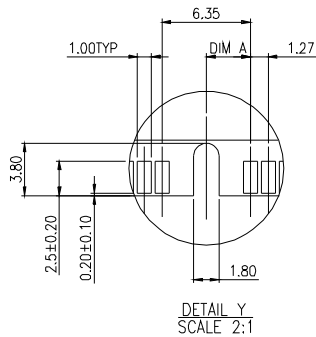
DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



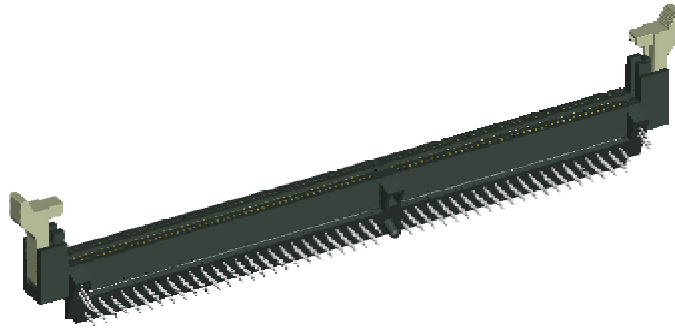
P.C. BOARD HOLE LAYOUT



DAUGHTER CARD REQUIREMENTS



DETAIL Y
SCALE 2:1

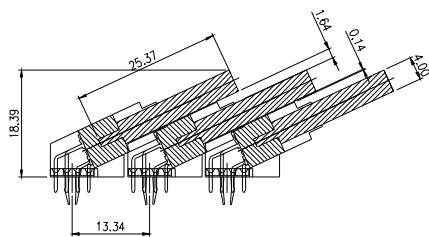
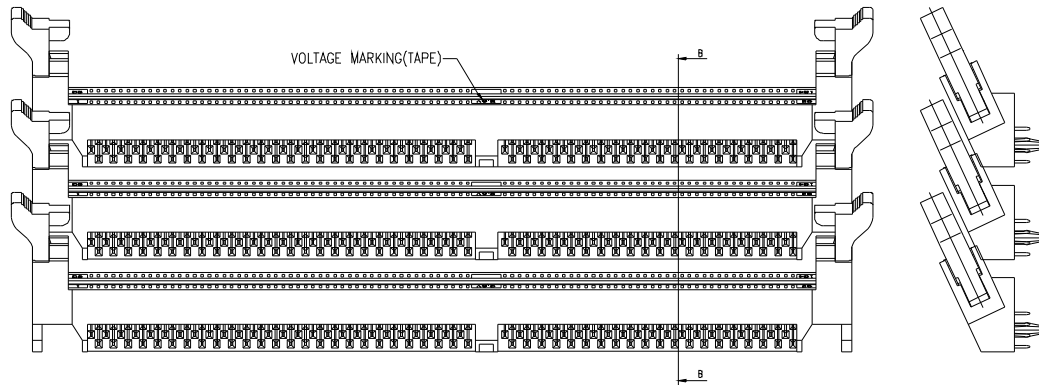
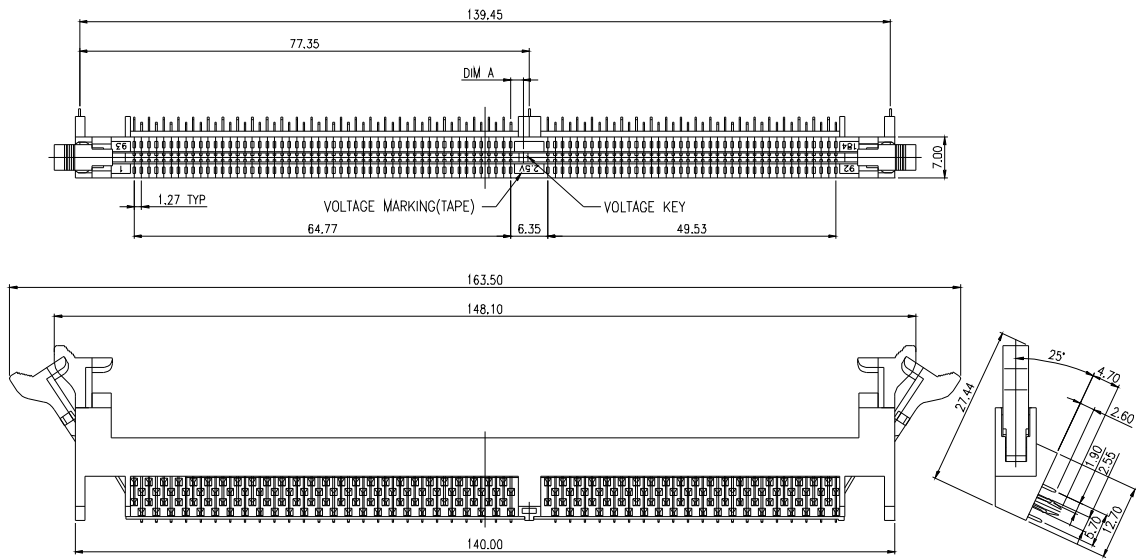


VOLTAGE	DIM A
1.8V	3.175
2.5V	2.175
3.3V	4.175

DIMM	104	Pr	184	GX	X	L	R
DIMM SOCKET		PCB TYPE Pr: RIGHT ANGLE 25 DEGREE TYPE	NO. OF PINS 184		VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V		INSERT TYPE R: REVERSE TYPE
SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM		CONTACT PLATING OPTION Gf: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL			HOUSING MATERIAL L: LCP		

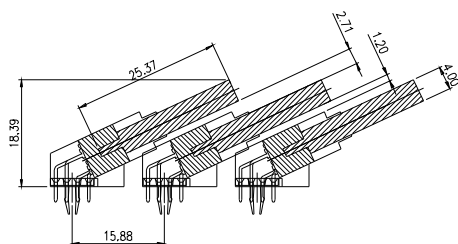
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr



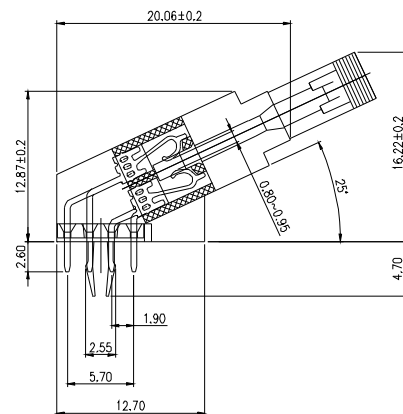
SECTION B-B(2:1)

MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 WILL LEAVE APPROXIMATELY 0.14 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



SECTION B-B(2:1)

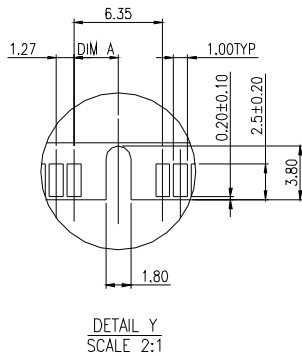
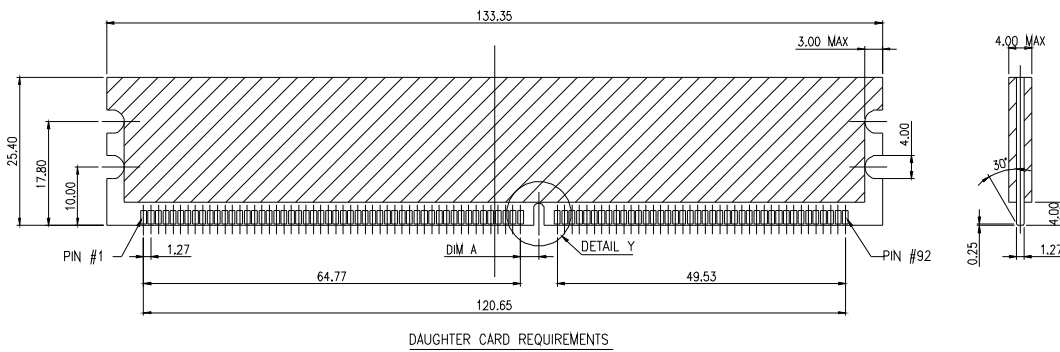
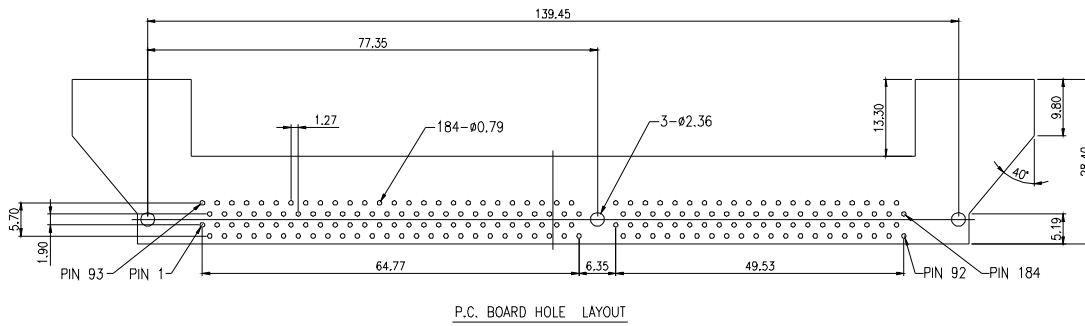
MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 15.88 WILL LEAVE APPROXIMATELY 1.21 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



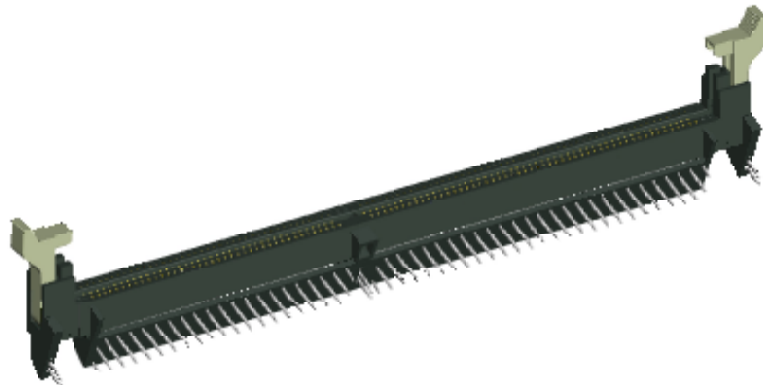
SECT A-A(2:1)

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



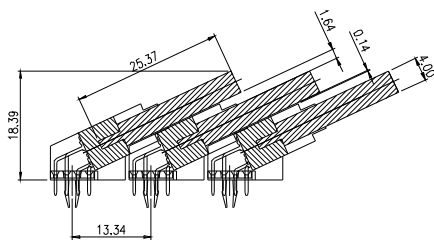
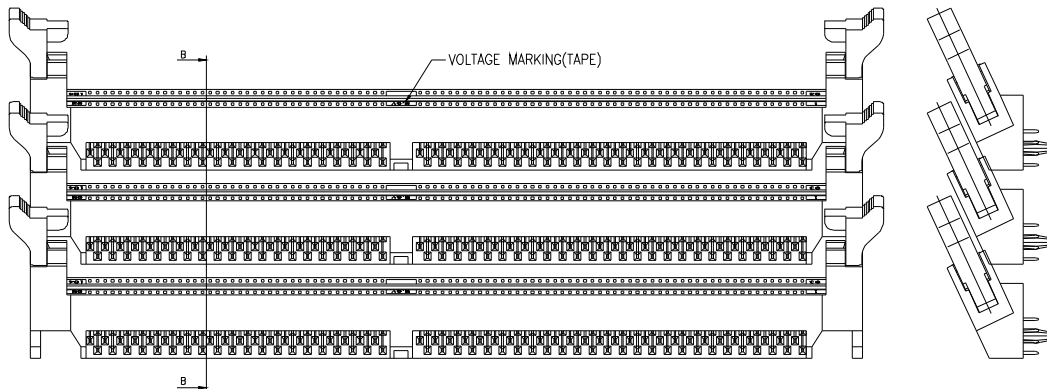
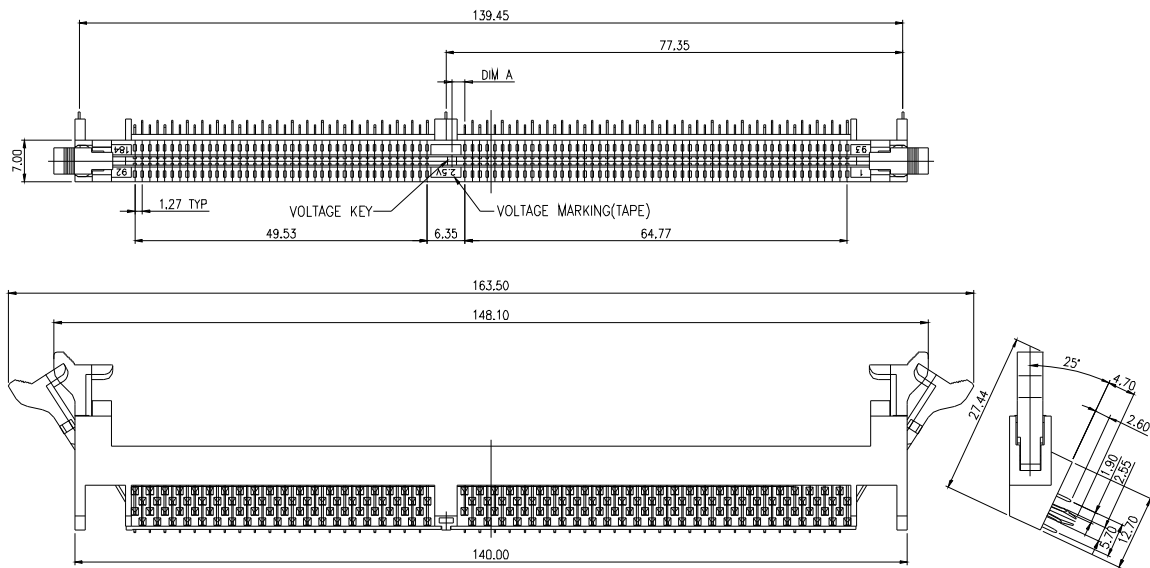
VOLTAGE	DIM A
1.8V	3.175
2.5V	2.175
3.3V	4.175



DIMM	104	Pr	184	GX	X	L	9
DIMM SOCKET		PCB TYPE Pr: RIGHT ANGLE 25 DEGREE TYPE	NO. OF PINS 184		VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V		ROW SPACING 9: 1.90mm
SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM		CONTACT PLATING OPTION Gf: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL			HOUSING MATERIAL L: LCP		

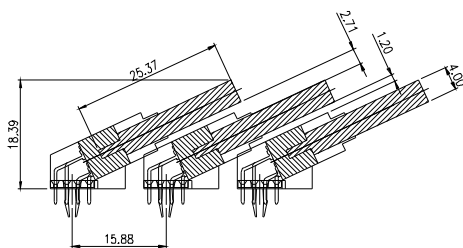
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



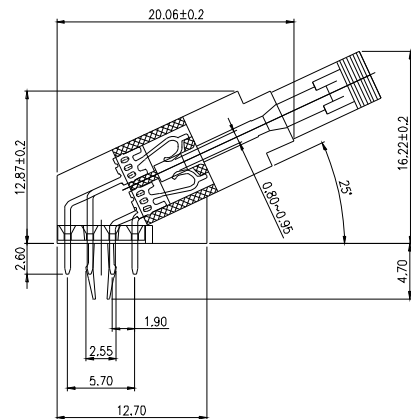
SECTION B-B(2:1)

MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 WILL LEAVE APPROXIMATELY 0.14 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



SECTION B-B(2:1)

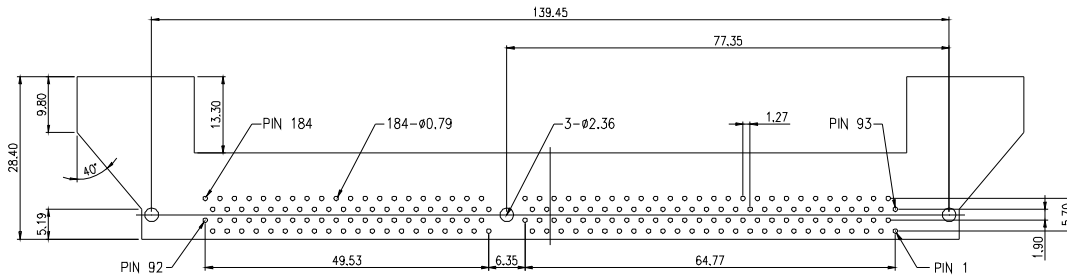
MINIMUM SOCKET TO SOCKET SPACING
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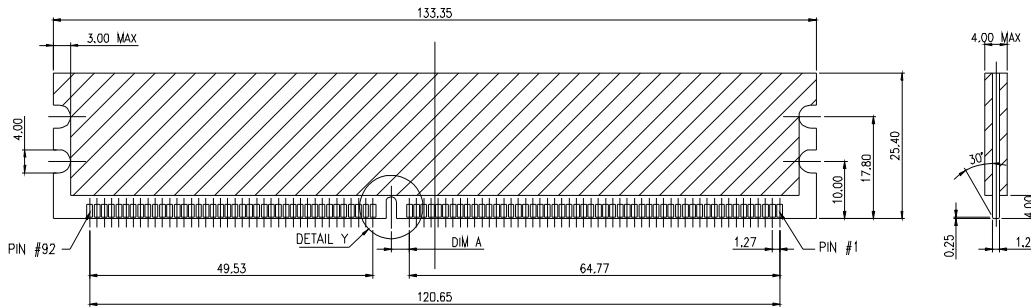
SECT A-A(2:1)

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

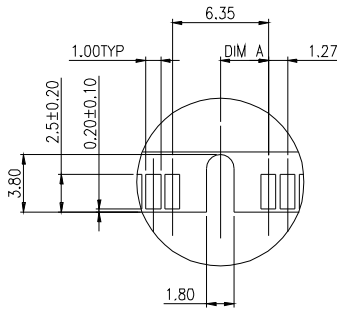
DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



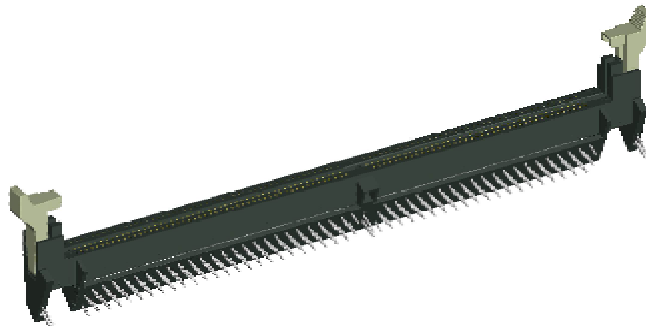
P.C. BOARD HOLE LAYOUT



DAUGHTER CARD REQUIREMENTS



DETAIL Y
SCALE 2:1



VOLTAGE	DIM A
1.8V	3.175
2.5V	2.175
3.3V	4.175

DIMM	104	Pr	184	GX	X	L	R	9
DIMM SOCKET		PCB TYPE Pr: RIGHT ANGLE 25 DEGREE TYPE	NO. OF PINS 184		VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V		INSERT TYPE R: REVERSE TYPE	
SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM		CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL						ROW SPACING 9: 1.90mm
				HOUSING MATERIAL L: LCP				

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE